Currents

CEDA
IEEE Council on Electronic Design Automation

Newsletter

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October 2024

- ICCAD 2024: Registration Open
- Phil Kaufman Award
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IEEE/ACM
IC CAD
2024 INTERNATIONAL CONFERENCE ON COMPUTER-AIDED DESIGN
43rd Edition

REGISTER NOW
📅 October 27–31, 2024   📍 Newark, NJ

ICCAD 2024: Registration Open

The International Conference on Computer-Aided Design focuses on advancements and research in the field of electronic design automation (EDA) and computer-aided design (CAD) for integrated circuits and systems. Topics include innovations in design methodologies, tools, algorithms, and technologies related to the development of electronic systems.

Date: 27-31 October 2024
Location: Newark, NJ, USA

Register Now

2024 Phil Kaufman Award

Dr. Jason Cong, Distinguished Professor and Volgenau Chair for Engineering Excellence at the University of California, Los Angeles (UCLA), will be honored with the 2024 **Phil Kaufman Award** for distinguished contributions to Electronic System Design (ESD) during the Phil Kaufman Award Ceremony and Banquet to be held 6 November 2024 in San Jose, California, USA at the Hayes Mansion. Dr. Cong is recognized "*for sustained fundamental contributions to Field-Programmable Gate Array (FPGA) design automation technology, from circuit to system levels, with widespread industrial impact.*"

In addition, Dr. Wojciech P. Maly, a pioneer in broad-spectrum research in electronic system design, will be inducted posthumously into the **Phil Kaufman Hall of Fame**.

If you would like to attend the award ceremony and banquet, you must pre-register.

Date: 6 November 2024
Location: Hayes Mansion, San Jose, CA, USA

DAC 2025: Call for Contributions

The call for contributions is now open for the 62nd DAC, Chips to Systems Conference taking place at Moscone West Center in San Francisco, CA, from June 22-25, 2025. This premier conference sponsored by IEEE CEDA and ACM SIGDA, offers a unique platform to present your research and insights to a global audience eager to drive innovation across sectors including AI, ML, high-performance computing, automotive, mobile technologies, security and more. Submit your contributions and pave the way for the next breakthroughs in electronic systems and chip design.

DAC is soliciting high-quality submissions on design research, design practices and design automation for the Research Track, Research Panels, Special Sessions, Engineering Tracks, Workshops and Tutorials. Submissions are also being sought for Late Breaking Results and Works-in-Progress.

Abstract Submission Deadline: 12 November 2024

Date: 22-25 June 2025
Location: San Francisco, CA, USA

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IEEE Embedded Systems Letters

IEEE ESL is soliciting submissions for its Special Issue on "Latest Advances in Embedded Systems Research in Latin America."

Latin America boasts a significant number of talented researchers working in the field of Embedded Systems. Although their valuable findings have been published extensively within their universities and region, they have yet to gain wider recognition abroad. However, this trend is starting to shift with events such as the Argentine Conference on Embedded Systems (CASE), which has formed partnerships with international publications. We believe that the advancements in Embedded Systems made in this region offer exciting contributions to the worldwide scientific community. This Special Issue aims to showcase the latest unpublished work on embedded systems from academia and industry in Latin America. It is targeted towards researchers, professors, students, and engineers who are interested in the latest developments in this field.

Suitable topics include, but are not limited, to the following:

- Embedded software
- Digital Signal Processing for embedded applications
- Modeling of Embedded Systems
- Embedded Systems' Methods and Tools
- Implementation and design of Embedded Systems

Submission Deadline: 11 November 2024

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IEEE Design&Test

IEEE D&T is soliciting submissions for its Special Issue on "Emerging Challenges with 3D NAND Flash Storage."

This special issue is dedicated to the design and test of 3D NAND flash storage in computing systems. It aims to cover diverse aspects of technology, foundry, design, EDA, test to in-field deployment, and integration into IoT, CPS, edge, and cloud solutions.

Topics of interest include:

- Computing in/near 3D NAND Flash storage
- Data sanitization issues in 3D NAND Flash storage
- 3D NAND Flash storage for harsh environments
- Sustainable practices for 3D NAND Flash storage
- 3D NAND Flash storage lifecycle management
- Latency enhancements for 3D NAND Flash storage
- Fault-tolerant 3D NAND Flash Storage Submission Guidelines
- Energy-efficient 3D NAND Flash storage
- Resource management for 3D NAND Flash storage
- Security vulnerabilities of 3D NAND Flash storage
- Supply chain security of 3D NAND Flash storage
- 3D NAND Flash for High-Performance Computing
- 3D NAND Flash for Embedded and IoT Computing

Submission Deadline: 1 February 2025

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IEEE CEDA System Validation and Debug Technology Council

IEEE P2929 Standard for System-level State Extraction for Functional Validation and Debug is progressing well. The standards WG team meets every Thursday between 8 to 9 AM PST and has made very good progress. The WG has completed most of the technical discussions for Scan and Array Extraction for debug purposes and is in the process of writing the standards document. The plan is to take it to balloting around the middle of next year (2025).

We welcome any of the interested attendees to join the Standards effort. Please reach out to Dr. Sankaran Menon at **smenon@ieee.org** for more information.

Learn More

Conferences

ACM/IEEE International Conference on Computer-Aided Design (**ICCAD 2024**)
📅 27-31 October 2024
📍 Newark, NJ, USA

Asia and South Pacific Design Automation Conference (**ASP-DAC 2025**)
📅 20-23 January 2025
📍 Tokyo, Japan

Design, Automation, and Test in Europe Conference (**DATE 2025**)

- 31 March-2 April 2025
- Lyon, France

Design Automation Conference (**DAC 2025**)

- 22-26 June 2025
- San Francisco, CA, USA

Embedded Systems Week (**ESWEEK 2025**)

- 2025 TBA
- 2025 TBA

Contact IEEE CEDA VP of Conferences Tsung-Yi Ho for sponsorship opportunities at **vp.conferences@ieee-ceda.org**.

Publications

IEEE CEDA financially sponsors and co-sponsors several publications and publishes its *Currents* newsletter to inform the EDA community on industry news and research results.

Visit the individual publication pages for more information on publication scope, call for papers, and more.

## Top Accessed Articles in September 2024 (*as of 11 October 2024)

IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems

- **ViA: A Novel Vision-Transformer Accelerator Based on FPGA**
- **NeuroSim: A Circuit-Level Macro Model for Benchmarking Neuro-Inspired Architectures in Online Learning**
- **TrueNorth: Design and Tool Flow of a 65 mW 1 Million Neuron Programmable Neurosynaptic Chip**

IEEE Design&Test

- **High-Bandwidth Memory (HBM) Test Challenges and Solution**
- **A Survey of Silicon Photonics for Energy-Efficient Manycore Computing**
- **A Reinforcement Learning Framework With Region-Awareness and Shared Path Experience for Efficient Routing in Networks-on-Chip**
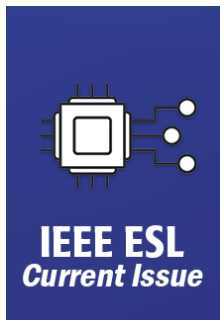
IEEE Embedded Systems Letters

- **An AI-Based Ventilation KPI Using Embedded IoT Devices**
- **On-Device Personalization for Human Activity Recognition on STM32**
- **Embedded Systems Education: Experiences With Application-Driven Pedagogy**

Contact IEEE CEDA VP of Publications Jörg Henkel at **henkel@kit.edu** or the journal's respective EiC for questions regarding CEDA-sponsored publications.

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